



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-10-05
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	SBVS*C20C2GC	A	Z45A	2015-10-05
Amount	UoM	Unit type	ST ECOPACK Grade	
4480.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.3X12.63X4.5	3	Through-hole	
Comment	Package:TOP3 ISOL. MD valid for CPs: <b>BTA26-600BRG - BTA26-700BRG - BTA26-800BRG</b>			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	SBVS*C20C2GC					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	16.607	mg	supplier	die	Silicon (Si)	7440-21-3		13.981	mg	841864	3121
				supplier	metallization	Nickel (Ni)	7440-02-0		1.000	mg	60219	223
				supplier	metallization	Gold (Au)	7440-57-5		0.100	mg	6022	22
				supplier	back side metallization	Gold (Au)	7440-57-5		0.018	mg	1084	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.380	mg	22883	85
				supplier	glass coating	Glass : Aluminium Oxide	1344-28-1		0.113	mg	6805	25
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	1.015	mg	61122	227
Leadframe	Copper & its alloys	2691.821	mg	supplier	alloy	Copper (Cu)	7440-50-8		2683.980	mg	997087	599103
				supplier	alloy	Iron (Fe)	7439-89-6		1.236	mg	459	276
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		2.258	mg	839	504
				supplier	metallization	Nickel (Ni)	7440-02-0		4.347	mg	1615	970
				JIG - R	Lead/Lead Compounds	Lead (Pb)	7439-92-1	7a. Lead in high me	24.919	mg	934977	5562
Soft solder	Solder	26.652	mg	supplier	Soft solder	Silver (Ag)	7440-22-4		0.400	mg	15008	89
				supplier	Soft solder	Tin (Sn)	7440-31-5		1.333	mg	50015	298
				supplier	Ceramic	Nickel (Ni)	7440-02-0		2.166	mg	11999	483
				supplier	Ceramic	Phosphorus (P)	12185-10-3		0.163	mg	903	36
Ceramic	Other inorganic materials	180.511	mg	supplier	Ceramic	Manganese (Mn)	7439-96-5		7.040	mg	39000	1571
				supplier	Ceramic	Titanium (Ti)	7440-32-6		0.740	mg	4099	165
				supplier	Ceramic	Molybdenum oxide	1313-27-5		9.025	mg	49997	2015
				supplier	Ceramic	Alumina (Al2O3)	1344-28-1		161.377	mg	894001	36022
				supplier	Other inorganic materials	Silica, vitreous	60676-86-0		1180.466	mg	760001	263497
				supplier	Other inorganic materials	Epoxy Cresol Novolak	29690-82-2		158.431	mg	102000	35364
Encapsulation	Other inorganic materials	1553.243	mg	supplier	mold compound	Phenol resin	9003-35-4		93.194	mg	60000	20802
				supplier	mold compound	Others	Proprietary		77.662	mg	50000	17335
				supplier	mold compound	Metal hydroxide	21645-51-2		31.064	mg	19999	6934
				supplier	mold compound	Carbon black	1333-86-4		12.426	mg	8000	2774
				Supplier	solder alloy	Tin (Sn)	7440-31-5		11.166	mg	1000000	2492
Finishing	Solder	11.166	mg	Supplier	solder alloy	Tin (Sn)	7440-31-5		11.166	mg	1000000	2492